12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	**20260715002.1**	**PCN Issued**	July 16, 2026
Qualification of a lead finish change and TI Clark as an additional Assembly site for select devices		**Sample request deadline:**	September 14, 2026
		Estimated 1st ship date:	October 14, 2026
Sample requests received after** September 14, 2026 will not be supported.**			

Change Type(s)	Assembly Site Assembly Material Packing/Shipping/Labeling

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a lead finish change and TI Clark as an additional Assembly site for select devices.

	Current Site	Current Site	Additional Site
Assembly/Test site	CDAT	CDAT	CLARK
Lead finish	NiPdAu	Matte Sn*	NiPdAu

*Applicable to LM51551DSSR

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Review the Standard Data Packet for more details on the changes
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

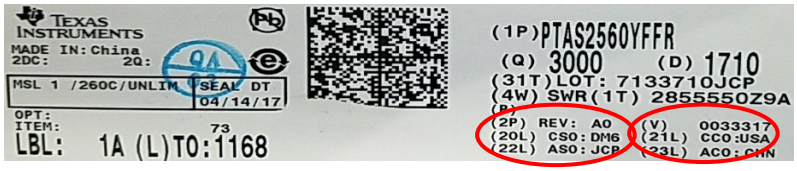
RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
CDAT	CDA	CHN	Chengdu
Clark	QAB	PHL	Pampanga

Sample product shipping label (not actual product label):



Products Affected:

LM51551DSSR	TPS55287RYQR	TPS55289RYQR
LM5155DSSR	TPS552892RYQR	
TPS552872RYQR	TPS552892RYQR.A	

Qualification Report

Approve Date 15-May -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS552872QWRYQRQ1	Qual Device: TPS552872QWRYQRQ1	Qual Device: TPS55289QWRYQRQ1	QBS Process Reference: TPS65033000QRGERQ1	QBS Package Reference: LMQ66430MC3RXBRQ1	QBS Product Reference: TPS552892QWRYQRQ1	QBS Package Reference: UCC33420QRAQRQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	3/All/0	-	3/All/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	-	3/231/0	-	3/231/0
UHAST	A3	Unbiased HAST	110C/85%RH	96 Hours	-	-	-	-	-	-	3/432/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	-	-	-
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	-	-	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-	3/231/0
HTSL	A6	High Temperature Storage Life	175C	500 Hours	1/45/0	-	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	1/10/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	1/6/0	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	-	-	-	-	3/90/0	-
FTY	E6	Final Test Yield	-	-	-	1/All/0	-	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device TPS552872QWRYQRQ1 is qualified at MSL2 260C
Qual Device TPS552872QWRYQRQ1 is qualified at MSL2 260C
Qual Device TPS55289QWRYQRQ1 is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2502-006

Qualification Report

Approve Date 01-JULY -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LM5155DSSR	QBS Package, Process Reference: LM5155DSST
HAST	A2	Biased HAST	130C/85%RH	96 Hours	QBS	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	QBS	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	QBS	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	QBS	3/231/0
FTY	E6	Final Test Yield	-	-	QBS	3/3/0
MQ		Assembly manufacturing qualification	TI internal specification		1 lot	

QBS: Qual By Similarity, also known as Generic Data
Qual Device LM5155DSSR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2507-028

Qualification Report

Approve Date 18-September-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TUSB1064RNQR	Qual Device: ADS8166IRHBR	Qual Device: BQ40Z552RSMR
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0	3/231/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	1/22/0	1/22/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device TUSB1064RNQR is qualified at MSL1 260C
Qual Device ADS8166IRHBR is qualified at MSL2 260C
Qual Device BQ40Z552RSMR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2402-114

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic

(family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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